

MMUN2232LT1 TRANSISTOR (NPN)

NPN Silicon Surface Mount Transistor with Monolithic Bias Resistor Network

This new series of digital transistors is designed to replace a single device and its external resistor bias network. The BRT (Bias Resistor Transistor) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. The BRT eliminates these individual components by integrating them into a single device. The use of a BRT can reduce both system cost and board space. The device is housed in the SOT-23 package which is designed for low power surface mount applications.

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- The SOT-23 package can be soldered using wave or reflow. The modified gull-winged leads absorb thermal stress during soldering eliminating the possibility of damage to the die.
- Available in 8 mm embossed tape and reel. Use the Device Number to order the 7 inch/3000 unit reel. Replace "T1" with "T3" in the Device Number to order the13 inch/10,000 unit reel.

MAXIMUM RATINGS (T_a=25℃ unless otherwise noted)

Symbol	Parameter	Value	Unit	
V _{CBO}	Collector-Base Voltage	50	V	
V _{CEO}	Collector-Emitter Voltage	50	V	
Ι _C	Collector Current	100	mA	
P _D	Total Power Dissipation @TA=25℃ Derate above 25℃	200 1.6	mW mW/℃	

THERMAL CHARACTERISTICS

Thermal Resistance — Junction-to-Ambient (surface mounted)	R _{0JA}	625	°C/W
Operating and Storage Temperature Range	TJ, Tstg	-65 to +150	°C
Maximum Temperature for Soldering Purposes, Time in Solder Bath	ΤL	260 10	°C Sec

DEVICE MARKING AND RESISTOR VALUES

Device	Marking	R1(K)	R2(K)
MMUN2211LT1	A8J	4.7	4.7

1. Device mounted on a FR-4 glass epoxy printed circuit board using the minimum recommended footprint.

2. New devices. Updated curves to follow in subsequent data sheets.

Thermal Clad is a trademark of the Bergquist Company

Preferred devices are Motorola recommended choices for future use and best overall value.

(Replaces MMUN2211T1/D)





Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =10uA ,I _E =0	50			V
Collector-emitter breakdown voltage	V(_{BR)CEO}	I _C =2mA ,I _B =0	50			V
Collector-Base cut-off current	I _{CBO}	V _{CB} =50V,I _E =0			100	nA
Collector-Emitter cut-off current	I _{CEO}	V_{CE} =50V,I _B =0			500	nA
Emitter- Base cut-off current	I _{EBO}	V _{EB} =6V,I _C =0			1.5	mA
DC current gain	h _{FE}	V _{CE} =10V,I _C =5mA	15	30		
Collector-emitter saturation voltage	V _{CE(sat)}	I _C =10 mA, I _B =1mA			0.25	V
Output voltage(on)	V _{OL}	V_{Cc} =5V, V_{B} =2.5V, R_{L} =1.0K Ω			0.2	V
Output voltage(off)	V _{OH}	V_{Cc} =5V, V_{B} =0.5V, R_{L} =1.0K Ω	4.9			V

ELECTRICAL CHARACTERISTICS (T_a=25[°]C unless otherwise specified)

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Characteristic	Symbol	Min	Тур	Max	Unit
Input resistor	R1	3.3	4.7	6.1	KΩ
Resistor ratio	R1/R2	0.8	1.0	1.2	

3. Pulse Test: Pulse Width < 300 $\mu s,$ Duty Cycle < 2.0%.